

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S146	1	"5711989".pn.	US-PGPUB; USPAT; EPO; JPO	OR	ON	2008/08/19 15:22
S147	1247	((((metal\$3 conduct\$3 viscous) near3 (paste medium ink slurry liquid solution adhesive glue)) solder\$3) same (detect\$3 recogniz\$3 inspect\$3 evaluat\$3 analyz\$3) and (((metal \$3 conduct\$3 viscous) near3 (paste medium ink slurry liquid solution adhesive glue)) solder \$3) with (((screen stencil) near3 print\$3) jet\$4 deposit\$3 apply \$3 dispens\$3 ink\$1jet drop\$4 microdroplet inject\$3) and (((metal \$3 conduct\$3 viscous) near3 (paste medium ink slurry liquid adhesive glue solution)) solder\$3) with (add\$3 add\$1on re \$1solder\$3 re\$1deposit \$3 re\$1print\$3 re \$1apply\$3 ((reiterat\$3 repeat\$3 again) near3 (print\$3 jet\$4 solder\$3 apply\$3 dispens\$3)))	USPAT; EPO; JPO	OR	ON	2008/08/19 15:35
S148	105	S147 and "29"/\$.cls.	USPAT; EPO; JPO	OR	ON	2008/08/19 15:36

S149	611	(((metal\$3 conduct\$3 viscous) near3 (paste medium ink slurry liquid solution adhesive glue)) solder\$3) same (detect\$3 recogniz\$3 inspect\$3 evaluat\$3 analyz\$3) and (((metal \$3 conduct\$3 viscous) near3 (paste medium ink slurry liquid solution adhesive glue)) solder \$3) with (((screen stencil) near3 print\$3) jet\$4 deposit\$3 apply \$3 dispens\$3 ink\$1jet drop\$4 microdroplet inject\$3) and (((metal \$3 conduct\$3 viscous) near3 (paste medium ink slurry liquid adhesive glue solution)) solder\$3) with (re\$solder\$3 re \$1deposit\$3 re\$1print \$3 re\$1apply\$3 ((reiterat\$3 repeat\$3 again add\$3 add\$1on) near3 (print\$3 jet\$4 solder\$3 apply\$3 dispens\$3)))	USPAT; EPO; JPO	OR	ON	2008/08/19 15:42
S150	73	S149 and "29"/\$.ccls.	USPAT; EPO; JPO	OR	ON	2008/08/19 15:43
S151	177	S149 and "228"/\$.ccls. not S150	USPAT; EPO; JPO	OR	ON	2008/08/19 16:26
S152	611	(((metal\$3 conduct\$3 viscous) near3 (paste medium ink slurry liquid solution adhesive glue)) solder\$3) same (detect\$3 recogniz\$3 inspect\$3 evaluat\$3 analyz\$3) and (((metal \$3 conduct\$3 viscous) near3 (paste medium ink slurry liquid solution adhesive glue)) solder \$3) with (((screen stencil) near3 print\$3) jet\$4 deposit\$3 apply \$3 dispens\$3 ink\$1jet drop\$4 microdroplet	USPAT; EPO; JPO	OR	ON	2008/08/20 11:18

		inject\$3) and (((metal\$3 conduct\$3 viscous) near3 (paste medium ink slurry liquid adhesive glue solution)) solder\$3) with (re\$1solder\$3 re\$1deposit\$3 re\$1print\$3 re\$1apply\$3 ((reiterat\$3 repeat\$3 again add\$3 add\$1on) near3 (print\$3 jet\$4 solder\$3 apply\$3 dispens\$3)))				
S153	73	S152 and "29"/\$.ccls.	USPAT; EPO; JPO	OR	ON	2008/08/20 11:18
S154	177	S152 and "228"/\$.ccls. not S153	USPAT; EPO; JPO	OR	ON	2008/08/20 11:18
S155	30	S152 and "174"/\$.ccls. not S153 not S154	USPAT; EPO; JPO	OR	ON	2008/08/20 11:18
S156	21	S152 and "427"/\$.ccls. not S153 not S154	USPAT; EPO; JPO	OR	ON	2008/08/20 11:27
S157	97	S152 and "257"/\$.ccls. not S153 not S154 not S155 not S156	USPAT; EPO; JPO	OR	ON	2008/08/20 11:35
S158	16	S152 and "361"/\$ not S153 not S154 not S155 not S156 not S157	USPAT; EPO; JPO	OR	ON	2008/08/20 12:00
S159	10	S152 and "438"/\$ not S153 not S154 not S155 not S156 not S157 not S158	USPAT; EPO; JPO	OR	ON	2008/08/20 12:02
S160	187	S152 not S153 not S154 not S155 not S156 not S157 not S158 not S159	USPAT; EPO; JPO	OR	ON	2008/08/20 12:05
S161	13	("3620230"   "3796153"   "4887623" "5027703"   "5095816"   "5197384" "5323700"   "5479854"   "5485781" "5786029"   "5976269"   "6036787" "6626106").PN. OR ("6923117").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/20 12:07

S162	10	("4864361"   "5280436"   "5459941" "5479854"   "5740729"   "5812693" "6140827").PN. OR ("6715413").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/20 12:27
S163	3	("3562481"   "5528214"   "5667128").PN. OR ("6797926").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/20 13:13
S164	10	("20030159783"   "5059266"   "5126529" "5196064"   "5260009"   "5681757" "5833914"   "6159772"   "6177714" "6503831").PN. OR ("6958095").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/20 13:14
S165	96	("4104645"   "4291316"   "4523199" "5059266"   "5132248"   "5149548" "5182571"   "5502585"   "5510066" "5539100"   "5705826"   "6059393" "6100954"   "6120588"   "6402403").PN. OR ("6503831").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/20 15:54
S166	16	("20020062909"   "20020083858"   "20020186287"   "20030059987"   "20030157244"   "20050258559"   "5141829"   "5204055" "5557690"   "5560799"   "5594652" "5660621"   "5841452"   "6019457" "6217148"   "6503831").PN. OR ("7373214").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/20 15:54

S167	4	(((metal\$3 conduct\$3 viscous) near3 (paste medium ink slurry liquid solution adhesive glue)) solder\$3) same (detect\$3 recogniz\$3 inspect\$3 evaluat\$3 analyz\$3) with (lack\$3 insufficient deficient inadequate scarce improper low little poor defect\$3) near3 amount and (((metal\$3 conduct\$3 viscous) near3 (paste medium ink slurry liquid solution adhesive glue)) solder\$3) with (((screen stencil) near3 print\$3) jet\$4 deposit\$3 apply\$3 dispens\$3 ink\$1jet drop\$4 microdroplet inject\$3) and (((metal\$3 conduct\$3 viscous) near3 (paste medium ink slurry liquid adhesive glue solution)) solder\$3) with (re\$1deposit\$3 re\$1print\$3 re\$1apply\$3 ((reiterat\$3 repeat\$3 again add\$3 add\$1on) near3 (print\$3 jet\$4 solder\$3 apply\$3 dispens\$3)))	USPAT; EPO; JPO	OR	ON	2008/08/20 16:19
S168	0	(((metal\$3 conduct\$3 viscous) near3 (paste medium ink slurry liquid solution adhesive glue)) solder\$3) same (detect\$3 recogniz\$3 inspect\$3 evaluat\$3 analyz\$3) with (lack\$3 insufficient deficient inadequate scarce improper low little poor defect\$3) near3 amount same (((screen stencil) near3 print\$3) jet\$4 deposit\$3 apply\$3 dispens\$3 ink\$1jet drop\$4 microdroplet	USPAT; EPO; JPO	OR	ON	2008/08/20 16:47

		inject\$3) and (((metal\$3 conduct\$3 viscous) near3 (paste medium ink slurry liquid adhesive glue solution)) solder\$3) with (re\$1deposit\$3 re\$1print\$3 re\$1apply\$3 ((reiterat\$3 repeat\$3 again add\$3 add\$1on) near3 (print\$3 jet\$4 solder\$3 apply\$3 dispens\$3))) not S167				
S169	33	(((metal\$3 conduct\$3 viscous) near3 (paste medium ink slurry liquid solution adhesive glue)) solder\$3) same (detect\$3 recogniz\$3 inspect\$3 evaluat\$3 analyz\$3) with (lack\$3 insufficient deficient inadequate scarce improper low little poor defect\$3) same (((screen stencil) near3 print\$3) jet\$4 deposit\$3 apply\$3 dispens\$3 ink\$1jet drop\$4 microdroplet inject\$3) and (((metal\$3 conduct\$3 viscous) near3 (paste medium ink slurry liquid adhesive glue solution)) solder\$3) with (re\$1deposit\$3 re\$1print\$3 re\$1apply\$3 ((reiterat\$3 repeat\$3 again add\$3 add\$1on) near3 (print\$3 jet\$4 solder\$3 apply\$3 dispens\$3))) not S167	USPAT; EPO; JPO	OR	ON	2008/08/20 16:48

S170	211	(((metal\$3 conduct\$3 viscous) near3 (paste medium ink slurry liquid solution adhesive glue)) solder\$3) with (detect\$3 recogniz\$3 inspect\$3 evaluat\$3 analyz\$3) and (lack\$3 insufficient deficient inadequate scarce improper low little poor defect\$3) same (((screen stencil) near3 print\$3) jet\$4 deposit \$3 apply\$3 dispens\$3 ink\$1jet drop\$4 microdroplet inject\$3) and (((metal\$3 conduct \$3 viscous) near3 (paste medium ink slurry liquid adhesive glue solution)) solder \$3) with (re\$1deposit \$3 re\$1print\$3 re \$1apply\$3 ((reiterat\$3 repeat\$3 again add\$3 add\$1on) near3 (print \$3 jet\$4 solder\$3 apply \$3 dispens\$3))) not S167 not S169	USPAT; EPO; JPO	OR	ON	2008/08/20 16:54
S171	34	(((metal\$3 conduct\$3 viscous) near3 (paste medium ink slurry liquid solution adhesive glue)) solder\$3) with (((screen stencil) near3 print\$3) jet\$4 deposit \$3 apply\$3 dispens\$3 ink\$1jet drop\$4 microdroplet inject\$3) same (detect\$3 recogniz\$3 inspect\$3 evaluat\$3 analyz\$3) same (re\$1deposit\$3 re \$1print\$3 re\$1apply\$3 ((reiterat\$3 repeat\$3 again add\$3 additional add\$1on) near3 (print \$3 jet\$4 solder\$3 apply \$3 dispens\$3))) not S167 not S169 not S170	USPAT; EPO; JPO	OR	ON	2008/08/20 17:08

S172	17	("3611077"   "4627730"   "5286414" "5486701").PN. OR ("6309691").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/20 17:13
S173	15	touch\$1up near3 print \$3	USPAT; EPO; JPO	OR	ON	2008/08/20 18:18
S174	14	solder\$3 with touch \$1up with print\$3 not S173	USPAT; EPO; JPO	OR	ON	2008/08/20 18:20
S175	17	("4821948"   "5065932"   "5193738" "5320273"   "5328085"   "5364011" "5415679"   "5746368"   "5774145" "5779971").PN. OR ("6076723").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/09/03 14:46
S176	17	("20020089067"   "5681757"   "6076723" "6121689"   "6291884"   "6307749" "6367150"   "6399426"   "6434817" "6518677"   "6566234"   "6766817" "6881591"   "6916684"   "6981317" "7022410"   "7028879").PN. OR ("7331106").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/09/03 14:47
S177	89	("3683212"   "5053100"   "5092864" "5187123"   "5227813"   "5235352" "5400064"   "5415679"   "5423889" "5426455"   "5435060"   "5436648" "5444467").PN. OR ("5681757").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/09/03 14:48
S178	17	("5120665"   "5123986"   "5283947" "5328087"   "5637176"   "5661042" "5681757"   "5839188"   "5843251" "6077382").PN. OR ("6315856").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/09/03 14:56



S179	12	("4657778"   "4870746"   "5048166" "5440805"   "5457881"   "5545281" "5557508"   "5570506"   "5603981" "5848462"   "6249962"   "6315856").PN. OR ("6604282").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/09/03 14:57
S180	31	("4515297"   "4803124"   "4874444" "4938383"   "4989796"   "5187123").PN. OR ("5423889").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/09/03 14:59
S181	496	((((metal\$3 conduct\$3 viscous\$3) near3 (paste medium ink slurry liquid solution adhesive glue)) solder \$3) with (detect\$3 recogniz\$3 inspect\$3 evaluat\$3 analyz\$3) and (((metal\$3 conduct \$3 viscous) near3 (paste medium ink slurry liquid solution adhesive glue)) solder \$3) with (((screen stencil) near3 print\$3) squeegee (doctor near2 blade) ((first bottom base) near3 (layer film))) and (((metal\$3 conduct\$3 viscous\$3) near3 (paste medium ink slurry liquid adhesive glue solution)) solder \$3) with (add\$3 add \$1 on re\$1 solder\$3 re \$1 deposit\$3 re\$1 print \$3 re\$1 apply\$3 ((reiterat\$3 repeat\$3 again addition\$2) near3 (print\$3 jet\$4 solder\$3 apply\$3 dispens\$3)))	USPAT; EPO; JPO	OR	ON	2008/09/03 17:01

S182	64	"29"/\$.ccls. and S181	US-PGPUB; USPAT; EPO; JPO	OR	ON	2008/09/03 17:02
S183	0	(((metal\$3 conduct\$3 viscous\$3) near3 (paste medium ink slurry liquid solution adhesive glue)) solder \$3) with (detect\$3 recogniz\$3 inspect\$3 evaluat\$3 analyz\$3) and (((metal\$3 conduct \$3 viscous) near3 (paste medium ink slurry liquid solution adhesive glue)) solder \$3) with (((screen stencil) near3 print\$3) squeegee (doctor near2 blade)) with (((first bottom base) near3 (layer film)) and (((metal\$3 conduct\$3 viscous\$3) near3 (paste medium ink slurry liquid adhesive glue solution)) solder \$3) with (add\$3 add \$1on re\$1solder\$3 re \$1deposit\$3 re\$1print \$3 re\$1apply\$3 ((reiterat\$3 repeat\$3 again addition\$2) near3 (print\$3 jet\$4 solder\$3 apply\$3 dispens\$3))) with (second next top addition\$2) near3 (layer film)	USPAT; EPO; JPO	OR	ON	2008/09/03 17:09
S184	3	(((metal\$3 conduct\$3 viscous\$3) near3 (paste medium ink slurry liquid solution adhesive glue)) solder \$3) with (detect\$3 recogniz\$3 inspect\$3 evaluat\$3 analyz\$3) and (((metal\$3 conduct \$3 viscous) near3 (paste medium ink slurry liquid solution adhesive glue)) solder	USPAT; EPO; JPO	OR	ON	2008/09/03 17:09

		<p>\$3) with (((screen stencil) near3 print\$3) squeegee (doctor near2 blade)) with (((first bottom base) near3 (layer film)) and (((metal\$3 conduct\$3 viscous\$3) near3 (paste medium ink slurry liquid adhesive glue solution)) solder \$3) with (add\$3 add \$1on re\$1solder\$3 re \$1deposit\$3 re\$1print \$3 re\$1apply\$3 ((reiterat\$3 repeat\$3 again addition\$2) near3 (print\$3 jet\$4 solder\$3 apply\$3 dispens\$3)))</p>				
S185	304	<p>(((metal\$3 conduct\$3 viscous\$3) near3 (paste medium ink slurry liquid solution adhesive glue)) solder \$3) with (detect\$3 recogniz\$3 inspect\$3 evaluat\$3 analyz\$3) and (((metal\$3 conduct\$3 viscous\$3) near3 (paste medium ink slurry liquid solution adhesive glue)) solder \$3) with (((screen stencil) near3 print\$3) squeegee (doctor near2 blade)) and (((metal\$3 conduct\$3 viscous\$3) near3 (paste medium ink slurry liquid adhesive glue solution)) solder \$3) with (add\$3 add \$1on re\$1solder\$3 re \$1deposit\$3 re\$1print \$3 re\$1apply\$3 ((reiterat\$3 repeat\$3 again addition\$2) near3 (print\$3 jet\$4 solder\$3 apply\$3 dispens\$3))) not S182 not S184</p>	USPAT; EPO; JPO	OR	ON	2008/09/03 17:11

S186	12	("3688582"   "4417782"   "4459456" "4459457"   "4623086"   "4657169" "4696101"   "4696104").PN. OR ("5234151").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/09/03 17:40
S187	25	("4704320"   "4729010"   "4761345" "4761518"   "4764435"   "4835065" "4873151").PN. OR ("5010388").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/09/03 17:44
S188	64	("2294513"   "3450044"   "3484654" "3622384"   "3630835"   "3808680" "3913219"   "4009087"   "4049844" "4155766"   "4158567"   "4197798" "4200044"   "4239001"   "4368281" "4371459"   "4470883"   "4479432" "4493789"   "4495546"   "4526474" "4555414"   "4595605"   "4616316" "4617557"   "4646634"   "4660991" "4666735"   "4670351"   "4775573" "4819558"   "4937585"   "4970768" "4981074"   "5011627"   "5033377" "5041187"   "5061551"   "5127330" "5131141"   "5148355"   "5201268" "5207950"   "5227223"   "5231268" "5344591"   "5362513"   "5366760" "5403649"   "5407741"   "5436091" "5461775"   "5503876"   "5540742").PN. OR ("5758575").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/09/03 17:48

S189	35	( "4537811"   "4665492"   "4944817" "5121329"   "5136515"   "5287435" "5340433"   "5340656"   "5622216" "5633021"   "5672380"   "5709905" "5733509"   "5758575"   "5764521" "5893404"   "5900207"   "5906863" "5980998"   "6010771"   "6243616" "6253116"   "6259962"   "6274412" "6510356"   "6547995"   "6548122").PN. OR ("6697694").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/09/03 17:48
S190	12	( "4866837"   "4941256"   "4953100" "4989082"   "5023916"   "5293324").PN. OR ("6047084").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/09/03 17:52

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